



May 1998
Revised May 2003

NC7SZ374

TinyLogic® UHS D-Type Flip-Flop with 3-STATE Output

General Description

The NC7SZ374 is a single positive edge-triggered D-type CMOS Flip-Flop with 3-STATE output from Fairchild's Ultra High Speed Series of TinyLogic® in the space saving SC70 6-lead package. The device is fabricated with advanced CMOS technology to achieve ultra high speed with high output drive while maintaining low static power dissipation over a very broad V_{CC} operating range. The device is specified to operate over the 1.65V–5.5V V_{CC} range. The inputs and output are high impedance when V_{CC} is 0V. Inputs tolerate voltages up to 7V independent of V_{CC} operating voltage. This single flip-flop will store the state of the D input that meets the setup and hold time requirements on the LOW-to-HIGH Clock (CP) transition. The output tolerates voltages above V_{CC} in the 3-STATE condition.

Features

- Space saving SC70 6-lead package
- Ultra small MicroPak™ leadless package
- Ultra High Speed; t_{PD} 2.6 ns Typ into 50 pF at 5V V_{CC}
- High Output Drive; ± 24 mA at 3V V_{CC}
- Broad V_{CC} Operating Range; 1.65V to 5.5V
- Matches the performance of LCX when operated at 3.3V V_{CC}
- Power down high impedance inputs/output
- Overvoltage tolerant inputs facilitate 5V – 3V translation
- Patented noise/EMI reduction circuitry implemented

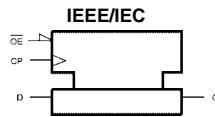
Ordering Code:

Order Number	Package Number	Product Code Top Mark	Package Description	Supplied As
NC7SZ374P6X	MAA06A	Z74	6-Lead SC70, EIAJ SC88, 1.25mm Wide	3k Units on Tape and Reel
NC7SZ374L6X	MAC06A	C9	6-Lead MicroPak, 1.0mm Wide	5k Units on Tape and Reel

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NC7SZ374 TinyLogic® UHS D-Type Flip-Flop with 3-STATE Output

Logic Symbol



Pin Descriptions

Pin Names	Description
D	Data Input
CP	Clock Pulse Input
\overline{OE}	Output Enable Input
Q	Flip-Flop Output

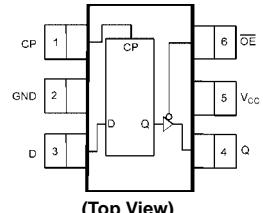
Function Table

Inputs			Output
CP	D	\overline{OE}	Q
/	L	L	L
/	H	L	H
\	X	L	Q_n
X	X	H	Z

H = HIGH Logic Level Z = High Impedance X = Immaterial
 L = LOW Logic Level Q_n = No change in data

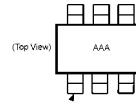
Connection Diagrams

Pin Assignments for SC70



(Top View)

Pin One Orientation Diagram

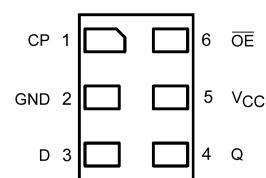


Pin One

AAA represents Product Code Top Mark - see ordering code

Note: Orientation of Top Mark determines Pin One location. Read the top product code mark left to right, Pin One is the lower left pin (see diagram).

Pad Assignment for MicroPak



(Top Thru View)

Absolute Maximum Ratings(Note 1)

Supply Voltage (V_{CC})	-0.5V to +7.0V
DC Input Voltage (V_{IN})	-0.5V to +7.0V
DC Output Voltage (V_{OUT})	-0.5V to +7.0V
DC Input Diode Current (I_{IK})	
$V_{IN} < 0V$	-50 mA
DC Output Diode Current (I_{OK})	
$V_{OUT} < 0V$	-50 mA
DC Output (I_{OUT}) Source/Sink Current	± 50 mA
DC V_{CC}/GND Current (I_{CC}/I_{GND})	± 50 mA
Storage Temperature Range (T_{STG})	-65°C to +150°C
Junction Temperature under Bias (T_J)	150°C
Junction Lead Temperature (T_L)	
(Soldering, 10 seconds)	260°C
Power Dissipation (P_D) @ +85°C	180 mW

Recommended Operating Conditions(Note 2)

Power Supply	V_{CC}	1.65V to 5.5V
Operating (V_{CC})		1.5V to 5.5V
Data Retention		0V to 5.5V
Input Voltage (V_{IN})		0V to V_{CC}
Output Voltage (V_{OUT})		0V to 5.5V
Active State		0V to V_{CC}
3-STATE		0V to 5.5V
Input Rise and Fall Time (t_r, t_f)		
$V_{CC} = 1.8V, 2.5V \pm 0.2V$		0 to 20 ns/V
$V_{CC} = 3.3V \pm 0.3V$		0 to 10 ns/V
$V_{CC} = 5.5V \pm 0.5V$		0 to 5 ns/V
Operating Temperature (T_A)		-40°C to +85°C
Thermal Resistance (θ_{JA})		350° C/W

Note 1: Absolute Maximum Ratings: are those values beyond which the safety of the device cannot be guaranteed. The device should not be operated at these limits. The parametric values defined in the Electrical Characteristics tables are not guaranteed at the absolute maximum ratings. The "Recommended Operating Conditions" table will define the conditions for actual device operation.

Note 2: Unused inputs must be held HIGH or LOW. They may not float.

DC Electrical Characteristics

Symbol	Parameter	V_{CC} (V)	$T_A = +25^\circ C$			Units	Conditions
			Min	Typ	Max		
V_{IH}	HIGH Level Control Input Voltage	1.65 to 1.95	0.75 V_{CC}		0.75 V_{CC}	V	
		2.3 to 5.5	0.75 V_{CC}		0.7 V_{CC}		
V_{IL}	LOW Level Control Input Voltage	1.65 to 1.95		0.25 V_{CC}	0.25 V_{CC}	V	
		2.3 to 5.5		0.3 V_{CC}	0.3 V_{CC}		
V_{OH}	HIGH Level Control Output Voltage	1.65	1.55	1.65	1.55	V	$I_{OH} = -100 \mu A$
		1.8	1.7	1.8	1.7		
		2.3	2.2	2.3	2.2		
		3.0	2.9	3.0	2.9		
		4.5	4.4	4.5	4.4		
		1.65	1.24	1.52	1.29		
		2.3	1.9	2.15	1.9		
		3.0	2.4	2.8	2.4		
		3.0	2.3	2.68	2.3		
		4.5	3.8	4.2	3.8		
V_{OL}	LOW Level Control Output Voltage	1.65	0.0	0.1	0.1	V	$I_{OL} = 100 \mu A$
		1.8	0.0	0.1	0.1		
		2.3	0.0	0.1	0.1		
		3.0	0.0	0.1	0.1		
		4.5	0.0	0.1	0.1		
		1.65	0.08	0.24	0.24		
		2.3	0.10	0.3	0.3		
		3.0	0.15	0.4	0.4		
		3.0	0.22	0.55	0.55		
		4.5	0.22	0.55	0.55		
I_{IN}	Input Leakage Current	0 to 5.5		± 0.1	± 1.0	μA	$0 \leq V_{IN} \leq 5.5V$
I_{OZ}	3-STATE Output Leakage	1.65 to 5.5		± 0.5	± 5.0	μA	$V_{IN} = V_{IL}$ or V_{IH} $0 \leq V_{OUT} \leq 5.5V$
I_{OFF}	Power Off Leakage Current	0.0		1.0	10	μA	V_{IN} or $V_{OUT} = 5.5V$
I_{CC}	Quiescent Supply Current	1.65 to 5.5		1.0	10.0	μA	$V_{IN} = 5.5V, GND$

AC Electrical Characteristics

Symbol	Parameter	V _{CC} (V)	T _A = +25°C		T _A = -40°C to +85°C		Units	Conditions	Figure Number	
			Min	Typ	Max	Min				
f _{MAX}	Maximum Clock Frequency	1.65				100	MHz	C _L = 50 pF R _D = 500Ω, S ₁ = Open	Figures 1, 3	
		1.8				100				
		2.5 ± 0.2				125				
		3.3 ± 0.3				150				
		5.0 ± 0.5				175				
t _{PLH} t _{PHL}	Propagation Delay CP to Q	1.65	2.5	9.7	1.50	2.5	16.5	ns	C _L = 15 pF R _D = 1 MΩ S ₁ = Open	Figures 1, 3
		1.8	2.5	6.5	10.0	2.5	11.0			
		2.5 ± 0.2	2.0	3.8	6.5	2.0	7.0			
		3.3 ± 0.3	1.5	2.8	4.5	1.4	5.0			
		5.0 ± 0.5	1.0	2.2	3.5	1.0	3.8			
		3.3 ± 0.3	2.0	3.4	5.5	1.6	6.2		C _L = 50 pF R _D = 500 Ω, S ₁ = Open	Figures 1, 3
		5.0 ± 0.5	1.5	2.6	4.0	1.4	4.7			
t _{PZL} t _{PZH}	Output Enable Time	1.65	2.0	9.0	13.5	2.0	14.3	ns	C _L = 50 pF, V _I = 2x V _{CC} R _U , R _D = 500 Ω S ₁ = GND for t _{PZH} S ₁ = V _I for t _{PZL}	Figures 1, 4
		1.8	2.0	6.0	9.0	2.0	9.5			
		2.5 ± 0.2	2.0	3.7	6.0	1.8	6.6			
		3.3 ± 0.3	1.5	2.8	5.0	1.4	5.3			
		5.0 ± 0.5	1.0	2.2	3.7	1.0	3.9			
t _{PLZ} t _{PHZ}	Output Disable Time	1.65	2.0	7.7	12.0	2.0	13.0	ns	C _L = 50 pF, V _I = 2x V _{CC} R _U , R _D = 500 Ω S ₁ = GND for t _{PHZ} S ₁ = V _I for t _{PLZ}	Figures 1, 4
		1.8	2.0	5.1	8.0	2.0	8.5			
		2.5 ± 0.2	2.0	3.5	6.0	1.8	6.3			
		3.3 ± 0.3	1.5	2.8	4.5	1.4	4.7			
		5.0 ± 0.5	1.0	2.3	3.7	1.0	3.9			
t _S	Setup Time, CP to D	2.5 ± 0.2				2.5		ns	C _L = 50 pF R _D = 500 Ω, S ₁ = Open	Figures 1, 5
		3.3 ± 0.3				2.0				
		5.0 ± 0.5				1.5				
t _H	Hold Time, CP to D	2.5 ± 0.2				1.5		ns	C _L = 50 pF D = 500 Ω, S ₁ = Open	Figures 1, 5
		3.3 ± 0.3				1.5				
		5.0 ± 0.5				1.5				
t _W	Pulse Width, CP	2.5 ± 0.2				3.0		ns	CL = 50 pF R _D = 500 Ω, S ₁ = Open	Figures 1, 5
		3.3 ± 0.3				2.8				
		5.0 ± 0.5				2.5				

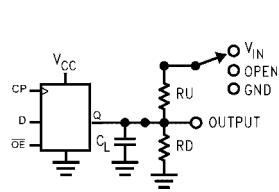
Capacitance (Note 3)

Symbol	Parameter	Typ	Max	Units	Conditions
C _{IN}	Input Capacitance	3		pF	V _{CC} = Open, V _{IN} 0V or V _{CC}
C _{OUT}	Output Capacitance	4		pF	V _{CC} = 3.3V, V _{IN} = 0V or V _{CC}
C _{PD}	Power Dissipation Capacitance (Note 4)	10		pF	V _{CC} = 3.3V V _{CC} = 5.0V
		12			

Note 3: T_A = +25°C, f = 1MHz.

Note 4: C_{PD} is defined as the value of the internal equivalent capacitance which is derived from dynamic operating current consumption (I_{CCD}) at no output loading and operating at 50% duty cycle. (See Figure 2) C_{PD} is related to I_{CCD} dynamic operating current by the expression:
I_{CCD} = (C_{PD}) (V_{CC}) (f_{IN}) + (I_{CC}static).

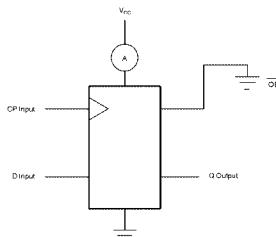
AC Loading and Waveforms



C_L includes load and stray capacitance

Input PRR = 1.0 MHz; t_w = 500 ns

FIGURE 1. AC Test Circuit



CP Input = AC Waveform; $t_r = t_f = 1.8$ ns;

CP Input PRR = 10 MHz; Duty Cycle = 50%

D Input PRR = 5MHz; Duty Cycle = 50%

FIGURE 2. I_{CCD} Test Circuit

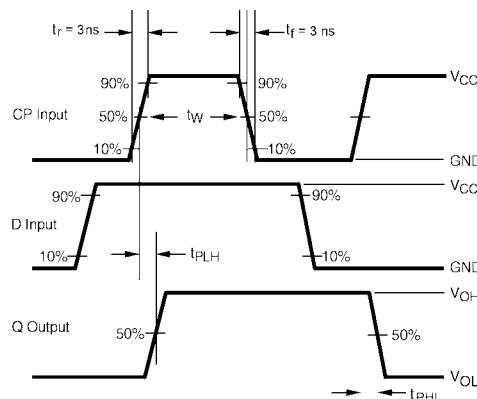


FIGURE 3. AC Waveforms

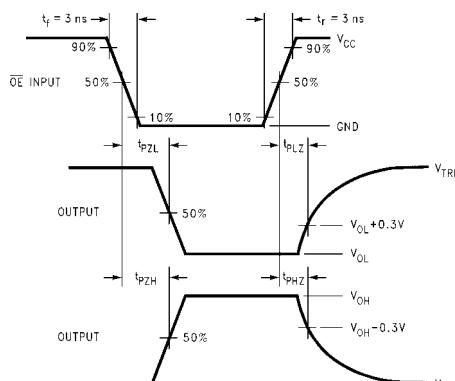


FIGURE 4. AC Waveforms

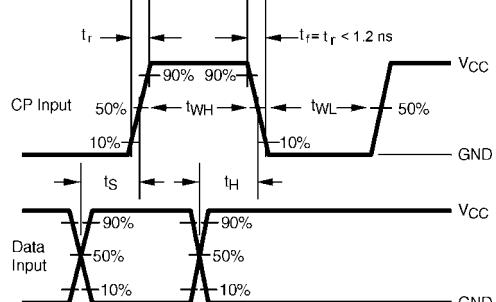


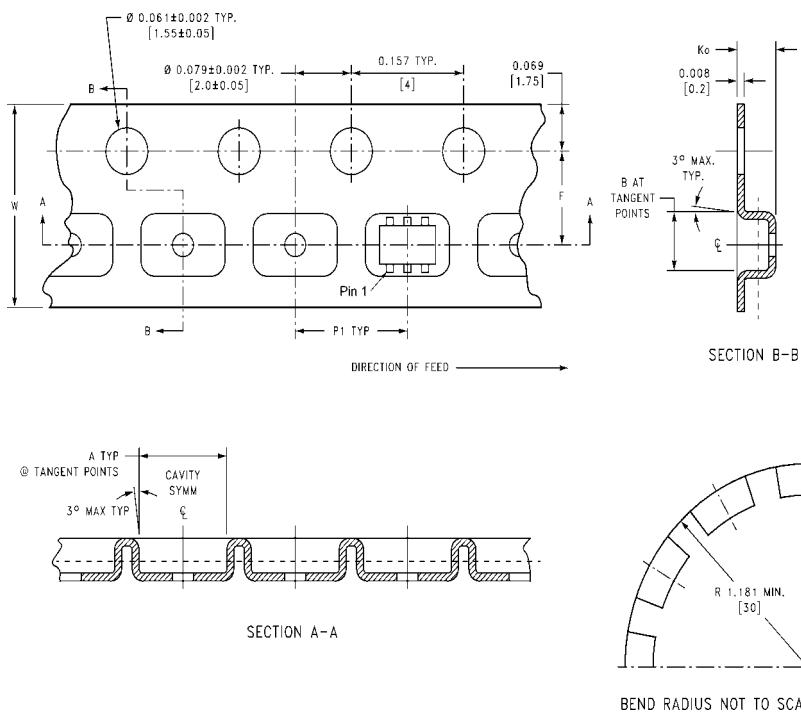
FIGURE 5. AC Waveforms

Tape and Reel Specification

TAPE FORMAT for SC70

Package Designator	Tape Section	Number Cavities	Cavity Status	Cover Tape Status
P6X	Leader (Start End)	125 (typ)	Empty	Sealed
	Carrier	3000	Filled	Sealed
	Trailer (Hub End)	75 (typ)	Empty	Sealed

TAPE DIMENSIONS inches (millimeters)

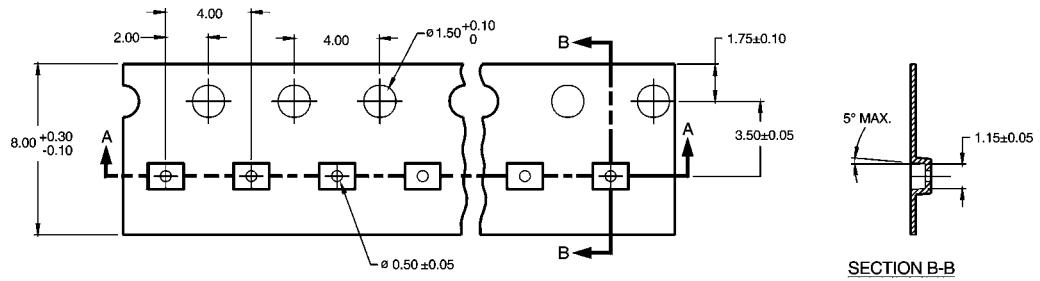


Package	Tape Size	DIM A	DIM B	DIM F	DIM K _o	DIM P1	DIM W
SC70-6	8 mm	0.093 (2.35)	0.096 (2.45)	0.138 ± 0.004 (3.5 ± 0.10)	0.053 ± 0.004 (1.35 ± 0.10)	0.157 (4)	0.315 ± 0.004 (8 ± 0.1)

Tape and Reel Specification (Continued)

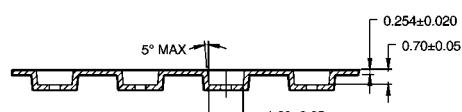
TAPE FORMAT for MicroPak

Package Designator	Tape Section	Number Cavities	Cavity Status	Cover Tape Status
L6X	Leader (Start End) Carrier Trailer (Hub End)	125 (typ) 5000 75 (typ)	Empty Filled Empty	Sealed Sealed Sealed



SECTION B-B

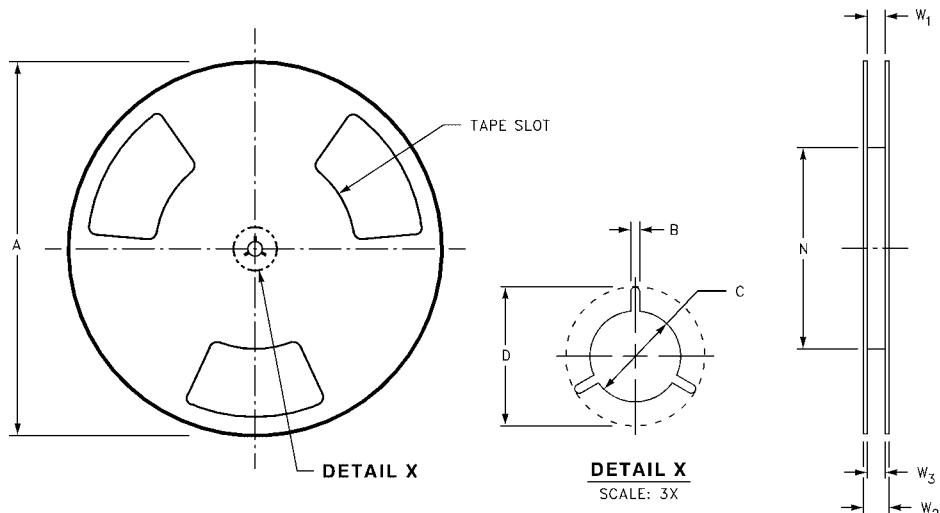
SCALE:10X



SECTION A-A

SCALE:10X

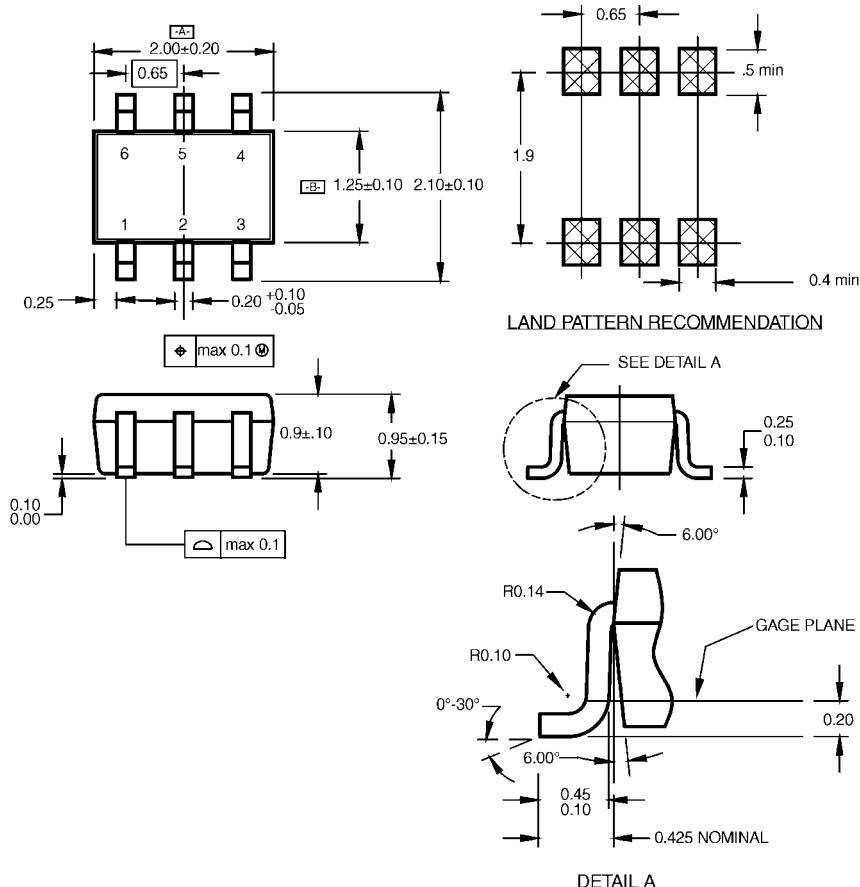
REEL DIMENSIONS inches (millimeters)



DETAIL X

SCALE: 3X

Tape Size	A	B	C	D	N	W1	W2	W3
8 mm	7.0 (177.8)	0.059 (1.50)	0.512 (13.00)	0.795 (20.20)	2.165 (55.00)	0.331 + 0.059/-0.000 (8.40 + 1.50/-0.00)	0.567 (14.40)	W1 + 0.078/-0.039 (W1 + 2.00/-1.00)

Physical Dimensions inches (millimeters) unless otherwise noted

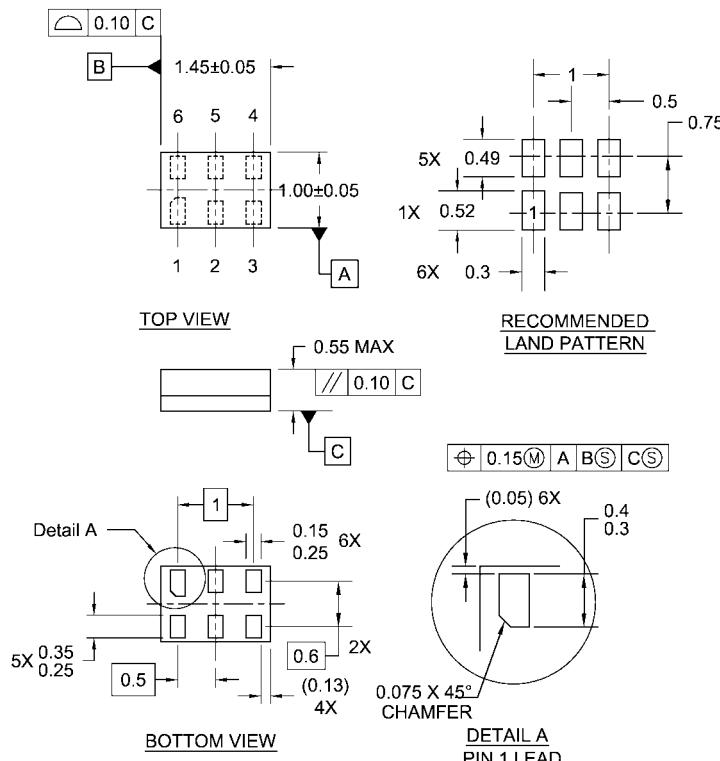
NOTES:

- A. CONFORMS TO EIAJ REGISTERED OUTLINE DRAWING SC88.
- B. DIMENSIONS DO NOT INCLUDE BURRS OR MOLD FLASH.
- C. DIMENSIONS ARE IN MILLIMETERS.

MAA06ARevC

6-Lead SC70, EIAJ SC88, 1.25mm Wide
Package Number MAA06A

Physical Dimensions inches (millimeters) unless otherwise noted (Continued)



Notes:

1. JEDEC PACKAGE REGISTRATION IS ANTICIPATED
2. DIMENSIONS ARE IN MILLIMETERS
3. DRAWING CONFORMS TO ASME Y14.5M-1994

MAC06ARevB

**6-Lead MicroPak, 1.0mm Wide
Package Number MAC06A**

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